

## Category Award IC & Components

### AirJet Mini Gen2



**FRORE SYSTEMS**

福珞爾台灣股份有限公司



### Winning Reason

The AirJet Mini G2 enables ultra-thin, silent, dust-proof, and waterproof systems with zero vibration. As the world's first and only solid-state active cooling chip, the AirJet Mini G2 is a low-profile, noise-free active cooler capable of removing 7.5W of heat at a back pressure of 1750 Pascals. With its superior thermal performance and exceptional environmental durability, it is purpose-built for Edge AI devices across a diverse range of applications.

### Product Feature

AirJet Mini G2 is the next-generation of the world's first solid-state active cooling chip, eliminating traditional fans and heatsinks with a thin, silent, and highly reliable solution. Using MEMS-based vibrating membranes, it generates high-velocity pulsating air jets to remove heat efficiently from compact enclosures. Designed for the rise of edge AI and AI reasoning models, AirJet Mini G2 delivers 50% higher heat dissipation in the same footprint, enabling sustained performance without thermal throttling. With 1750 Pa back pressure (~10× fans), 21 dBA silent operation, and no moving parts, it enables sleek, dustproof, water-resistant, vibration-free devices. Building on an award-winning platform, AirJet Mini G2 transforms thermal management into a chip-level solution.

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